



## ABSTRACT OF THE DISCLOSURE

Forming solder bumps each having a constant height by surely supplying onto each of electrode pads a solder ball corresponding to a predetermined volume while omitting Au plating performed on the electrode pads onto which the solder bumps are to be formed. For achieving the forming of the solder bumps, the adhesive film is formed instead of the Au plating, the adhesive film being used as an oxidation-preventing film and as film for temporarily fixing each of the solder balls, the solder balls being supplied by stencil mask or the vacuum adsorbing mask.